

LXA15T600

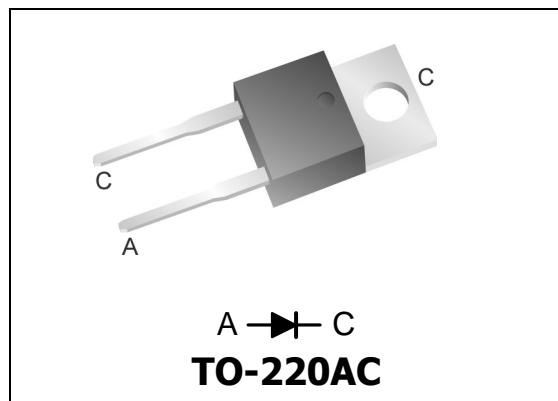
Qspeed™ Family

600 V, 15 A X-Series PFC Diode

Product Summary

I _{F(AVG)}	15	A
V _{RRM}	600	V
Q _{RR} (Typ at 125 °C)	120	nC
I _{RRM} (Typ at 125 °C)	4.6	A
Softness t _b /t _a (Typ at 125 °C)	0.45	

Pin Assignment



RoHS Compliant

Package uses Lead-free plating and
Green mold compound.
Halogen free per IEC 61249-2-21.

Absolute Maximum Ratings

Absolute maximum ratings are the values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.

Symbol	Parameter	Conditions	Rating	Units
V _{RRM}	Peak repetitive reverse voltage		600	V
I _{F(AVG)}	Average forward current	T _J = 150 °C, T _C = 101 °C	15	A
I _{FSM}	Non-repetitive peak surge current	60 Hz, ½ cycle	95	A
I _{FSM}	Non-repetitive peak surge current	½ cycle of t=28 µs Sinusoid, T _C =25 °C	350	A
T _{J(MAX)}	Maximum junction temperature		150	°C
T _{STG}	Storage temperature		-55 to 150	°C
	Lead soldering temperature	Leads at 1.6 mm from case, 10 sec	300	°C
P _D	Power dissipation	T _C = 25 °C	96	W

Thermal Resistance

Symbol	Resistance from:	Conditions	Rating	Units
R _{θJA}	Junction to ambient	TO-220	62	°C/W
R _{θJC}	Junction to case	TO-220	1.3	°C/W

General Description

This device has the lowest Q_{RR} of any 600 V Silicon diode. Its recovery characteristics increase efficiency, reduce EMI and eliminate snubbers.

Applications

- Power Factor Correction (PFC) boost diode
- Motor drive circuits
- DC-AC inverters

Features

- Low Q_{RR}, low I_{RRM}, low t_{RR}
- High dI_F/dt capable (1000 A/µs)
- Soft recovery

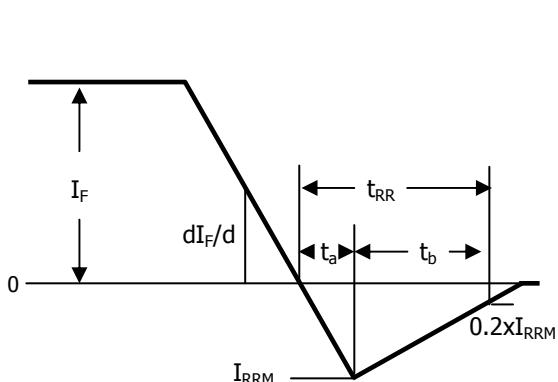
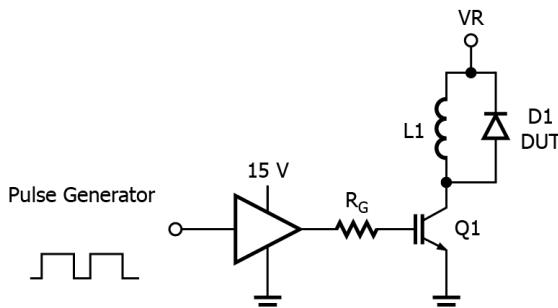
Benefits

- Increases efficiency
 - Eliminates need for snubber circuits
 - Reduces EMI filter component size & count
- Enables extremely fast switching

Electrical Specifications at $T_J = 25^\circ\text{C}$ (unless otherwise specified)

Symbol	Parameter	Conditions	Min	Typ	Max	Units	
DC Characteristics							
I_R	Reverse current	$V_R = 600 \text{ V}, T_J = 25^\circ\text{C}$	-	-	250	μA	
		$V_R = 600 \text{ V}, T_J = 125^\circ\text{C}$	-	1.7	-	mA	
V_F	Forward voltage	$I_F = 15 \text{ A}, T_J = 25^\circ\text{C}$	-	2.5	3.1	V	
		$I_F = 15 \text{ A}, T_J = 150^\circ\text{C}$	-	2.2	-	V	
C_J	Junction capacitance	$V_R = 10 \text{ V}, 1 \text{ MHz}$	-	71	-	pF	
Dynamic Characteristics							
t_{RR}	Reverse recovery time	$dI/dt = 200 \text{ A}/\mu\text{s}$ $V_R = 400 \text{ V}, I_F = 15 \text{ A}$	$T_J = 25^\circ\text{C}$	-	25	-	ns
			$T_J = 125^\circ\text{C}$	-	39	-	ns
Q_{RR}	Reverse recovery charge	$dI/dt = 200 \text{ A}/\mu\text{s}$ $V_R = 400 \text{ V}, I_F = 15 \text{ A}$	$T_J = 25^\circ\text{C}$	-	43	67	nC
			$T_J = 125^\circ\text{C}$	-	120	-	nC
I_{RRM}	Maximum reverse recovery current	$dI/dt = 200 \text{ A}/\mu\text{s}$ $V_R = 400 \text{ V}, I_F = 15 \text{ A}$	$T_J = 25^\circ\text{C}$	-	2.7	3.6	A
			$T_J = 125^\circ\text{C}$	-	4.6	-	A
S	Softness factor = $\frac{t_b}{t_a}$	$dI/dt = 200 \text{ A}/\mu\text{s}$ $V_R = 400 \text{ V}, I_F = 15 \text{ A}$	$T_J = 25^\circ\text{C}$	-	0.7	-	
			$T_J = 125^\circ\text{C}$	-	0.45	-	

Note to component engineers: X-Series diodes employ Schottky technologies in their design and construction. Therefore, Component Engineers should plan their test setups to be similar to those for traditional Schottky test setups. (For additional details, see Application Note AN-300.)


Figure 1. Reverse Recovery Definitions


PI-7614-041315

Figure 2. Reverse Recovery Test Circuit

Electrical Specifications at $T_J = 25^\circ\text{C}$ (unless otherwise specified)

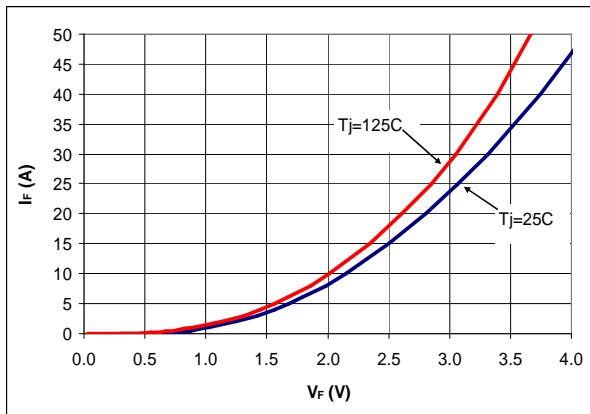


Figure 3. Typical I_F vs V_F

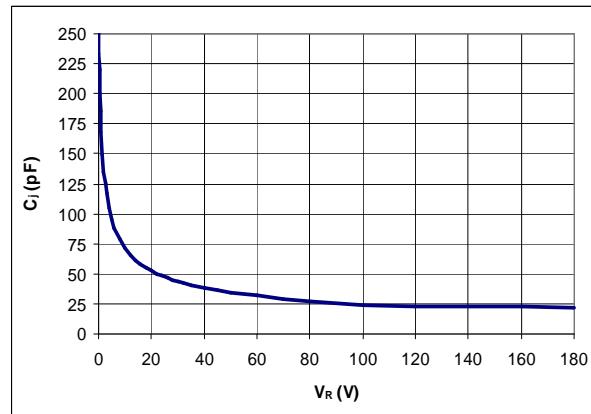


Figure 4. Typical C_j vs V_R

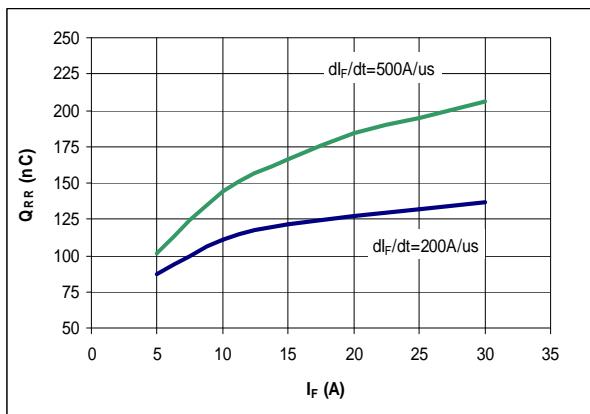


Figure 5. Typical Q_{RR} vs I_F at $T_J = 125^\circ\text{C}$

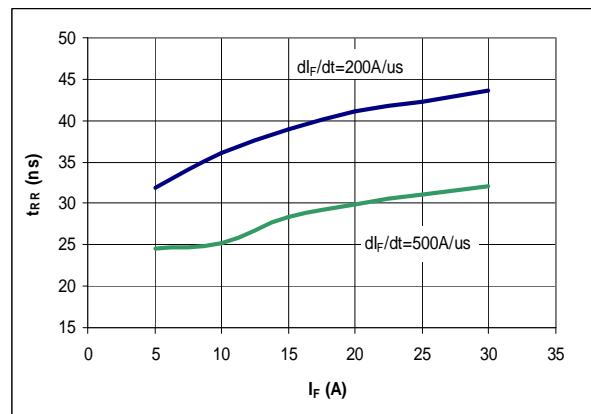


Figure 6. Typical t_{RR} vs I_F at $T_J = 125^\circ\text{C}$

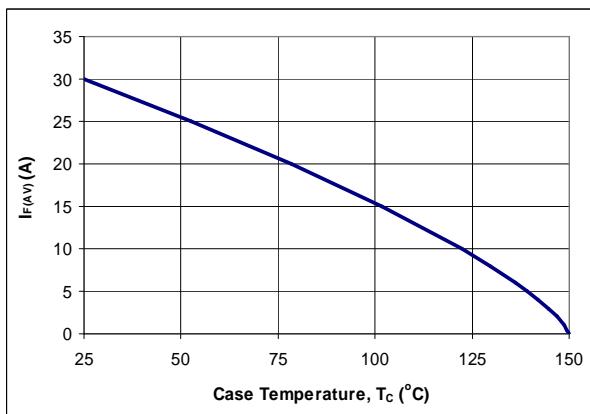


Figure 7. DC Current Derating Curve

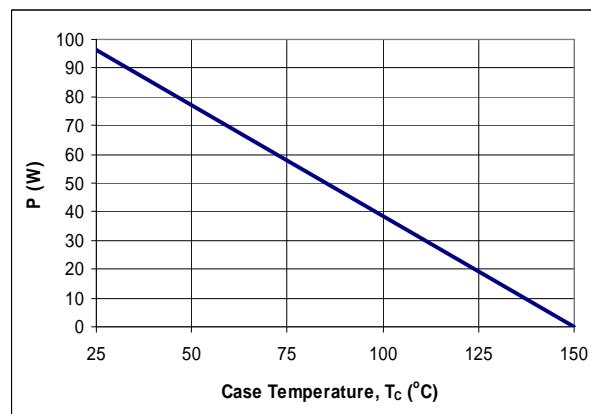


Figure 8. Power Derating Curve

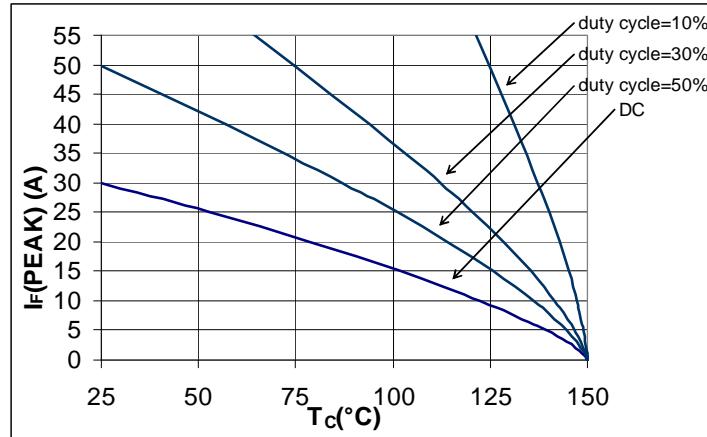


Figure 9. $I_F(\text{PEAK})$ vs T_C , $f=70$ kHz

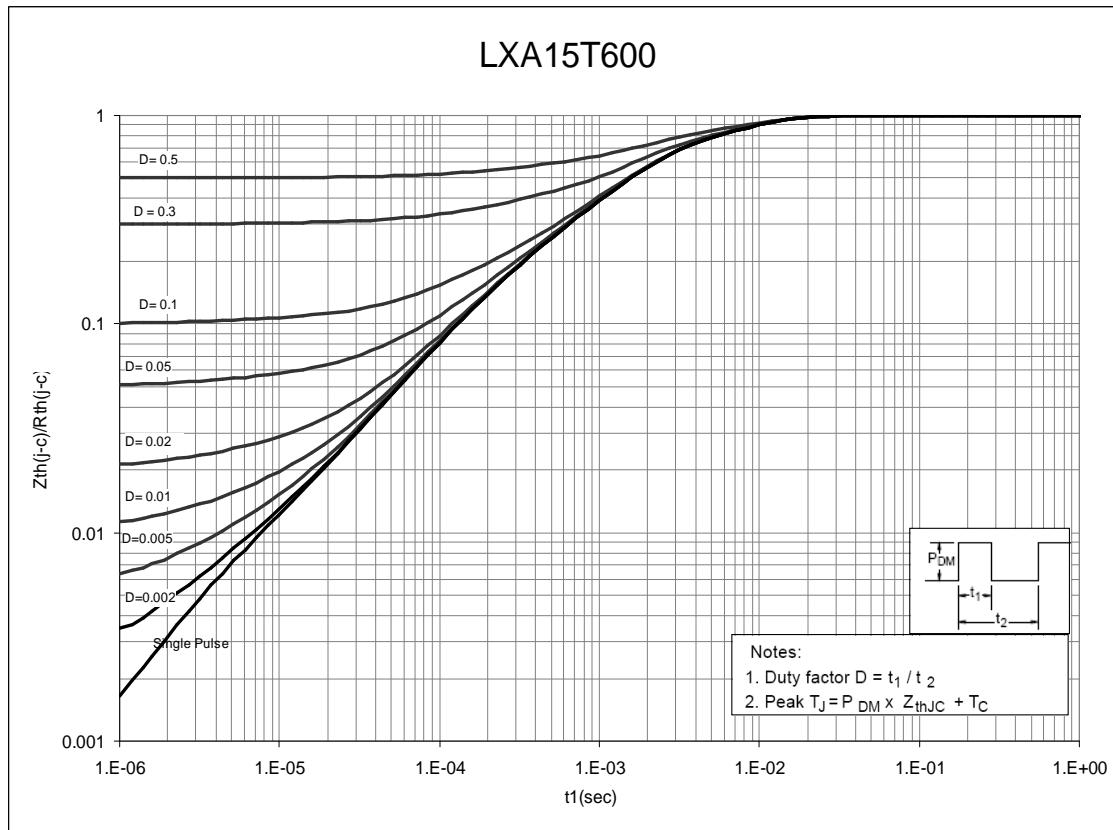
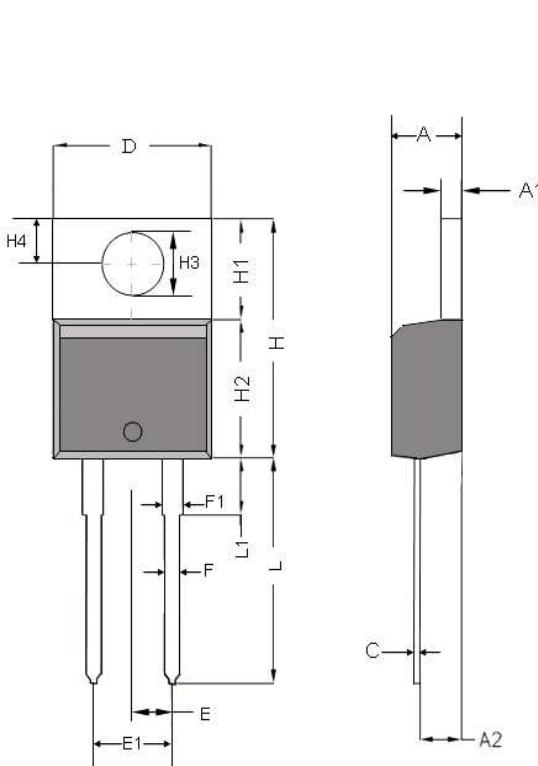


Figure 10. Normalized Maximum Transient Thermal Impedance

Dimensional Outline Drawings



	Millimeters	
Dim	MIN	MAX
A	4.32	4.70
A1	1.14	1.40
A2	2.03	2.79
C	0.34	0.610
D	9.65	10.67
E	2.49	2.59
E1	4.98	5.18
F	0.508	1.016
F1	1.14	1.78
H	14.71	16.51
H1	5.84	6.55
H2	8.51	9.25
H3	3.53	3.96
H4	2.54	3.05
L	12.70	14.22
L1	-	6.35

Mechanical Mounting Method	Maximum Torque / Pressure specification
Screw through hole in package tab	1 Newton Meter (nm) or 8.8 inch-pounds (lb-in)
Clamp against package body	12.3 kilogram-force per square centimeter (kgf/cm ²) or 175 lbf/in ²

Soldering time and temperature: This product has been designed for use with high-temperature, lead-free solder. The component leads can be subjected to a maximum temperature of 300 °C, for up to 10 seconds. See Application Note AN-303, for more details.

Ordering Information

Part Number	Package	Packing
LXA15T600	TO-220AC	50 units/tube

The information contained in this document is subject to change without notice.

LXA15T600

Revision	Notes	Date
1.0	Released by Qspeed	08/09
1.1	Converted to Power Integrations Document	01/11
1.1	Stop Point of t_{RR} error corrected due to typo in Figure 1	11/13
1.2	Updated with new Brand Style.	06/15

For the latest updates, visit our website: www.power.com

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